

L Number	Hits	Search Text	DB	Time stamp
-	90	nikoonahad-m\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/01 12:06
-	79	nikoonahad-m\$.in. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:36
-	63	nikoonahad-mehrdad\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:36
-	57	nikoonahad-mehrdad\$.in. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:38
-	38	nikoonahad-mehrdad\$.in. and scatter\$.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:40
-	22	nikoonahad-mehrdad\$.in. and (scatter\$ and rotat\$).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 15:41
-	486	scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm.	USPAT	2004/06/02 18:01
-	253	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm.	USPAT	2004/06/02 13:57
-	46	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/04 12:05
-	46	356/\$.ccls. and scatter\$.ab. and ((semiconductor or wafer) near4 surface) and rotat\$ and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/02 14:14
-	115	(356/\$ or 250/\$).ccls. and scatter\$.ab. and x\$lay and (semiconductor or wafer)	USPAT	2004/06/02 14:16
-	31	(356/\$ or 250/\$).ccls. and scatter\$.ab. and x\$lay and (semiconductor or wafer) and x\$lay.clm.	USPAT	2004/06/02 17:12
-	35	(356/\$ or 250/\$).ccls. and scatter\$.ab. and (x\$lay near6 source) and (semiconductor or wafer)	USPAT	2004/06/02 17:56
-	11	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946").pn.	USPAT	2004/06/04 17:28
-	4	("6429943" "6433878" "6483580" "6451621").pn.	USPAT	2004/06/02 18:00
-	4	scatter\$.ab. and ((semiconductor or wafer) near4 surface) and (neural adj network)	USPAT	2004/06/04 15:55
-	2	("6399944" "6316151").pn.	USPAT	2004/06/04 15:33
-	10	("4999014" "5042951" "5181080" "5329357" "5412473" "5596411" "5608526" "5771094" "5747813" "5917594" "6323946" "6429943" "6433878" "6483580" "6451621").pn. and rotat\$	USPAT	2004/06/03 16:13

-	24	("4039370" "4141780" "4200396" "4303341" "4330213" "4408884" "4710642" "4905170" "5164790" "5241369" "5329357" "5381233" "5416594" "5607800" "5608526" "5739909" "5757671" "5835221" "5867276" "5923423" "5956148" "5963329" "6031615" "6118525").PN.	USPAT	2004/06/03 16:14
-	15	("4039370" "4141780" "4200396" "4303341" "4330213" "4408884" "4710642" "4905170" "5164790" "5241369" "5329357" "5381233" "5416594" "5607800" "5608526" "5739909" "5757671" "5835221" "5867276" "5923423" "5956148" "5963329" "6031615" "6118525").PN.	USPAT	2004/06/03 16:15
-	12	and rotat\$ ("4039370" "4141780" "4200396" "4303341" "4330213" "4408884" "4710642" "4905170" "5164790" "5241369" "5329357" "5381233" "5416594" "5607800" "5608526" "5739909" "5757671" "5835221" "5867276" "5923423" "5956148" "5963329" "6031615" "6118525").PN.	USPAT	2004/06/03 16:15
-	4	and scatter\$ and rotat\$ ("4710642" "5164790" "5241369" "5703692").PN.	USPAT	2004/06/03 16:26
-	3	("4710642" "5164790" "5241369" "5703692").PN. and scatter\$ and rotat\$	USPAT	2004/06/03 16:26
-	80	356/372.ior.	USPAT	2004/06/04 11:30
-	4	356/372.ior. and scatter\$.ab.	USPAT	2004/06/04 11:30
-	1514	356/\$.cor. and scatter\$.ab.	USPAT	2004/06/04 11:31
-	1299	356/\$.cor. and scatter\$.ab. and scatter\$.clm.	USPAT	2004/06/04 11:31
-	478	356/\$.cor. and scatter\$.ab. and scatter\$.clm. and @pd>19980101	USPAT	2004/06/04 11:32
-	208	356/\$.cor. and scatter\$.ab. and scatter\$.clm. and @pd>19980101 and (semiconductor or wafer)	USPAT	2004/06/04 11:38
-	13	356/340.ccls. and scatter\$.clm. and (semiconductor or wafer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 11:47
-	50	356/301.ccls. and scatter\$.clm. and (semiconductor or wafer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 11:48
-	1	("5164790").pn.	USPAT	2004/06/04 11:50
-	49	356/237.1,237.2-237.5.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT	2004/06/04 12:06
-	49	356/237.1,237.2-237.5.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 16:17
-	9	356/335-343.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/06/04 13:31
-	1	356/239.1-239.8.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and rotat\$.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/01 13:22
-	3	("6115117" "5867276" "6556303").pn.	USPAT	2004/06/04 17:28

-	98	356/\$.cor. and scatter\$.ab. and scatter.clm. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 12:10
-	81	356/\$.cor. and scatter\$.ab. and scatter.clm. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 12:16
-	116	356/\$.ccls. and scatter\$.ab. and scatter.clm. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 12:10
-	37	356/336,338,340,343.ccls. and scatter\$.ab. and scatter.clm. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 12:11
-	45	250/\$.cor. and scatter\$.ab. and scatter.clm. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 12:25
-	905	250/559.19-559.24.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:19
-	487	250/559.26-559.28.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:19
-	47	(250/559.19-559.24.ccls. or 250/559.26-559.28.ccls.) and scatter\$.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:19
-	39	(250/559.19-559.24.ccls. or 250/559.26-559.28.ccls.) and scatter\$.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:19
-	0	356/239.1-239.8.ccls. and ((semiconductor or wafer) near4 surface) and scatter\$.clm. and @pd>20040604	USPAT; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:23
-	0	356/239.1-239.8.ccls. and (semiconductor or wafer) and scatter\$.clm. and @pd>20040604	USPAT; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:23
-	17	356/237.1,237.2-237.5.ccls. and (semiconductor or wafer) and scatter\$.clm. and @pd>20040604	USPAT; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:26
-	1	356/301.ccls. and (semiconductor or wafer) and scatter\$.clm. and @pd>20040604	USPAT; EPO; JPO; DERWENT; IBM_TDB USPÄT	2004/11/01 13:27
-	5	("20040070772" "20040017574" "20030206298" "20020101585" "20020051564").pn.	US-PGPUB	2004/11/01 13:30
-	4	("20040070772" "20040017574" "20030206298" "20020101585" "20020051564").pn. and rotat\$	US-PGPUB	2004/11/01 13:33
-	0	(6,721,052 6,704,661 6,694,284 6,694,275 6,689,519).pn.	US-PGPUB	2004/11/01 13:33

-	5	(6,721,052 6,704,661 6,694,284 6,694,275 6,689,519).pn.	USPAT	2004/11/01 13:34
-	2	(6,721,052 6,704,661 6,694,284 6,694,275 6,689,519).pn. and rotat\$	USPAT	2004/11/01 13:36
-	9	(6,665,071 6,645,824 6,636,843 6,633,831 6,608,690 6,608,686 6,583,731 6,483,580 6,451,621 6,433,878).pn.	USPAT	2004/11/01 13:36
-	3	(6,665,071 6,645,824 6,636,843 6,633,831 6,608,690 6,608,686 6,583,731 6,483,580 6,451,621 6,433,878).pn. and rotat\$	USPAT	2004/11/01 13:38
-	10	(6,429,943 6,323,946 6,124,924 5,771,094 5,747,813 5,608,526 5,604,344 5,596,411 5,412,473 5,329,357).pn.	USPAT	2004/11/01 13:38
-	6	(6,429,943 6,323,946 6,124,924 5,771,094 5,747,813 5,608,526 5,604,344 5,596,411 5,412,473 5,329,357).pn. and rotat\$	USPAT	2004/11/01 13:39
-	3	(5,181,080 5,042,951 4,999,014).pn. and rotat\$	USPAT	2004/11/01 13:40
-	280	356/630,636.ccls. and rotat\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/11/05 14:58